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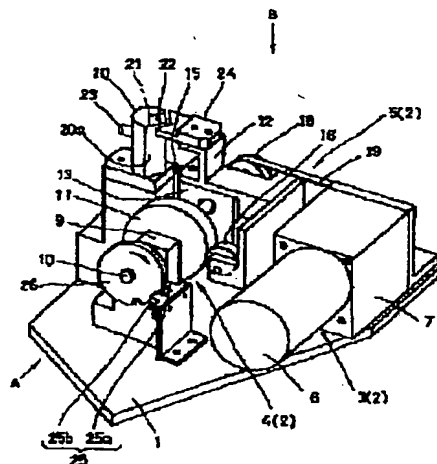
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(54) DIE POSITIONING DEVICE

(57) Abstract:

PURPOSE: To reduce the size of a die positioning device and, at the same time, to increase the degree of freedom in the location of installation of an automatic bonder.

CONSTITUTION: A positioning pawl 24 is installed to a slider 12 and an air hole 21 for sucking a die 21 is opened through a positioning table 20. A spring 15 forcible pushes the slider 12 toward the table 20 and a bearing 18 installed to the slider 12 supports the slider 12 while the bearing 16 is brought into contact with a cam 11. When the cam 11 is rotated by means of a motor 8, the extended end section of the pawl 24 is brought into contact with two adjacent sides of the die 21 and moves the die 21 until the die 21 comes into contact with the table 20. The die 21 is moved (positioned) to a prescribed position while the die 21 is rotated around the hole 22 to correct its attitude.



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